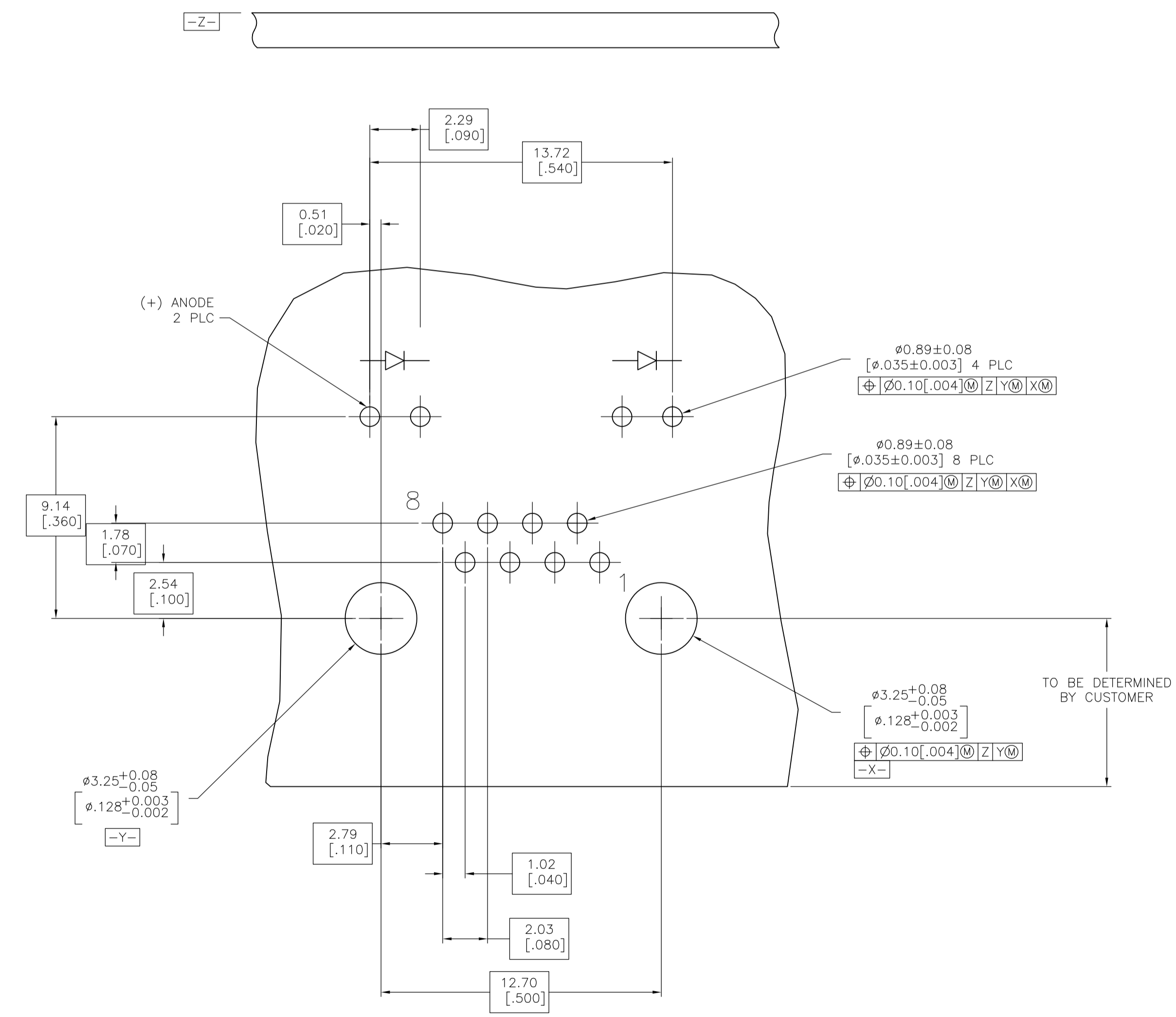


- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0.  
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, .51 x .51[.020 x .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.  
 ⚠ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.  
 ⚠ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

INDICATOR COLOR	POSITION 2	POSITION 1	PART NUMBER
GREEN	-	-	1-406533-7
GREEN	RED/GREEN	-	1-406533-0
YELLOW	YELLOW	-	406533-6
YELLOW	-	-	406533-3
-	GREEN	-	406533-2
YELLOW	GREEN	-	406533-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN T SPRINKLE 17SEP97	CHK T SPRINKLE 17SEP97	APVD M DERSTINE 17SEP97	NAME
	0 PLC ± -				INVERTED MODULAR JACK ASSEMBLY, 1X1, LED
	1 PLC ± -				108-1163-4
	2 PLC ± 0.25(.010)				APPLICATION SPEC
	3 PLC ± 0.13(.005)				114-2154
	4 PLC ± -				SIZE CAGE CODE DRAWING NO
	ANGLES ± -				A1 00779 C=406533
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT			RESTRICTED TO
					CUSTOMER DRAWING

SCALE 8:1 SHEET 1 OF 1 REV G